

TLE9845 Application Kit N User's Manual

Product Family: TLE984xQX

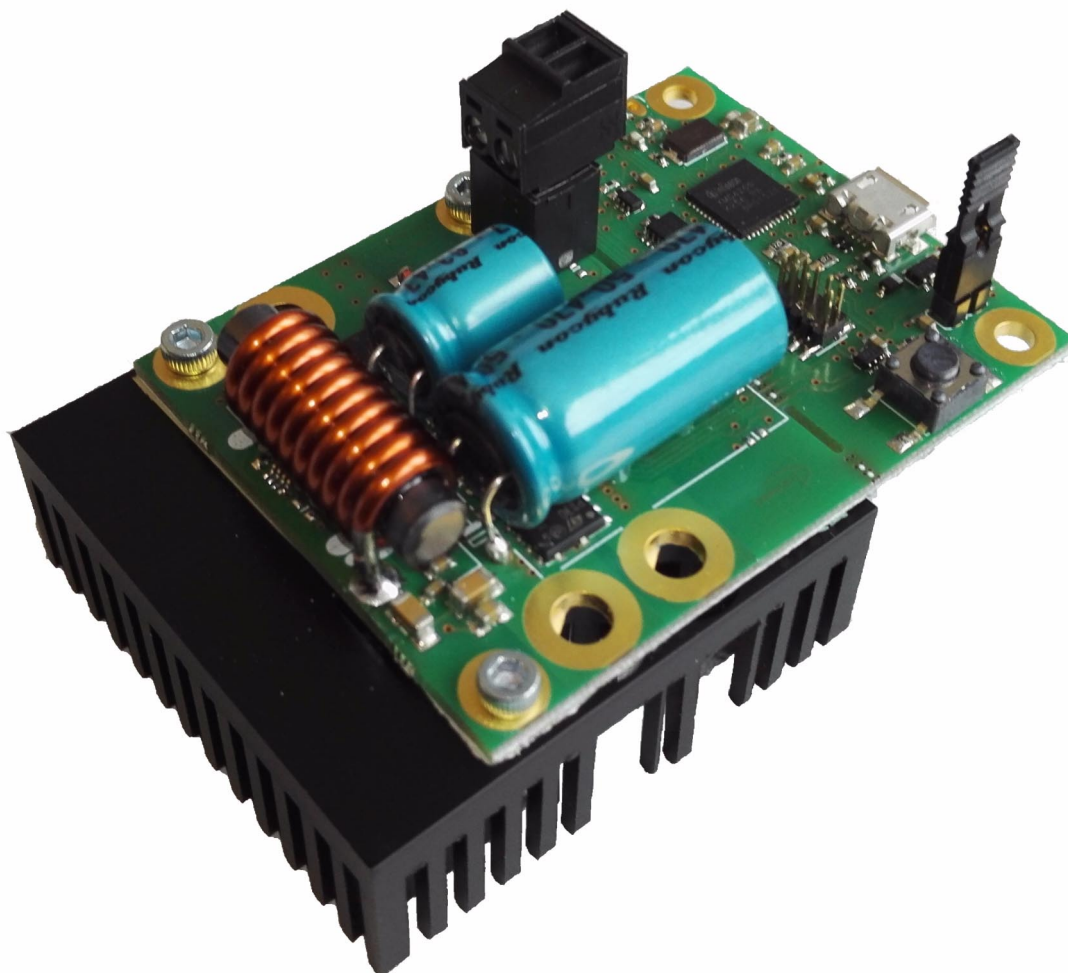


Figure 1 TLE9845QX Application Kit with Low Side N-Channel MOSFETs

About this document

Scope and purpose

The TLE9845_APPKIT_N is designed to evaluate hardware and software functionalities of the TLE9845QX in an application similar designed shape. The n-channel MOSFET is placed as a Low Side Switch. A passive freewheeling diode is placed to drive DC motors unidirectionally.

This documentation describes the basic use of the TLE9845_APPKIT_N, a TLE9845 32-bit ARM Cortex M0 Core, its functionality and how to get started with an application running on the evaluation board.

Note: This Evaluationboard is not optimized for EMC behavior.

Intended audience

This Document is for everyone who works with the TLE9845_N_APPKIT

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Concept

1 Concept

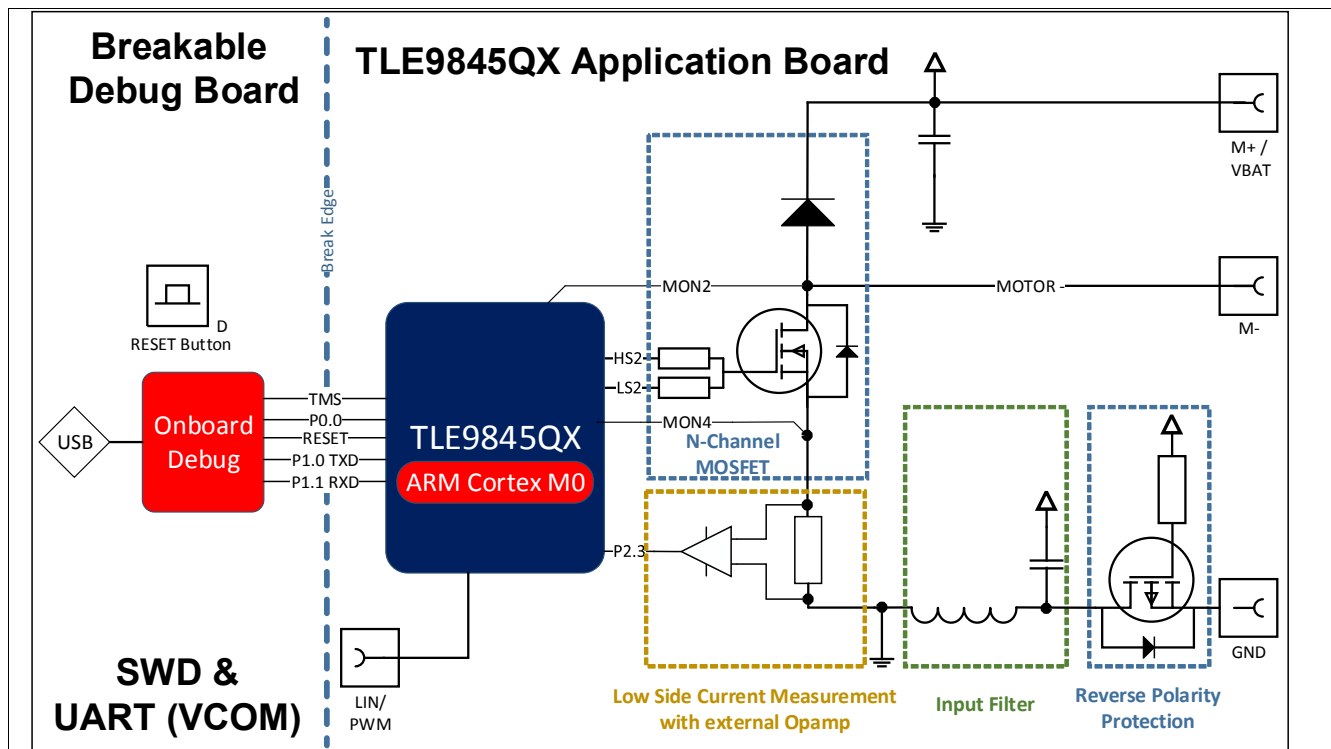


Figure 2 N Application Kit Concept

The TLE9845_App_Kit_N provides an application near circuit to evaluate unidirectional DC motors. The lowside MOSFET with passive power diode can be used to evaluate motor connected to battery applications. The TLE9845QX device is placed underneath the DC-link capacitor. The board is protected against reverse polarity of input voltage supply.

The N-channel MOSFET is connected to the integrated highside and lowside switches of the TLE9845QX Device.

In addition a lowside current sense resistor is placed with an external operational amplifier. It is connected to the ADC1 (P2.3).

The Application Kit provides a breakable On-Board debugger. It provides a SWD-Debug connection and a virtual COM port for serial UART communication.

Power supply and motor connectors are accessible via plated through hole contacts, which can be used to place M2.5 pressnuts (optionally).

Board features:

- Application near circuit (Motor connected to Battery)
- Overcurrent Protection (external lowside Shunt)
- Drain-Source-Monitoring (Differential Unit)
- USB-Communication and Debug-Interface (USB-Connector)
- Demo-Application Code and Graphical User Interface (GUI)
- LIN-PWM Example Code (PWM Generator with GUI)

2 Interconnections

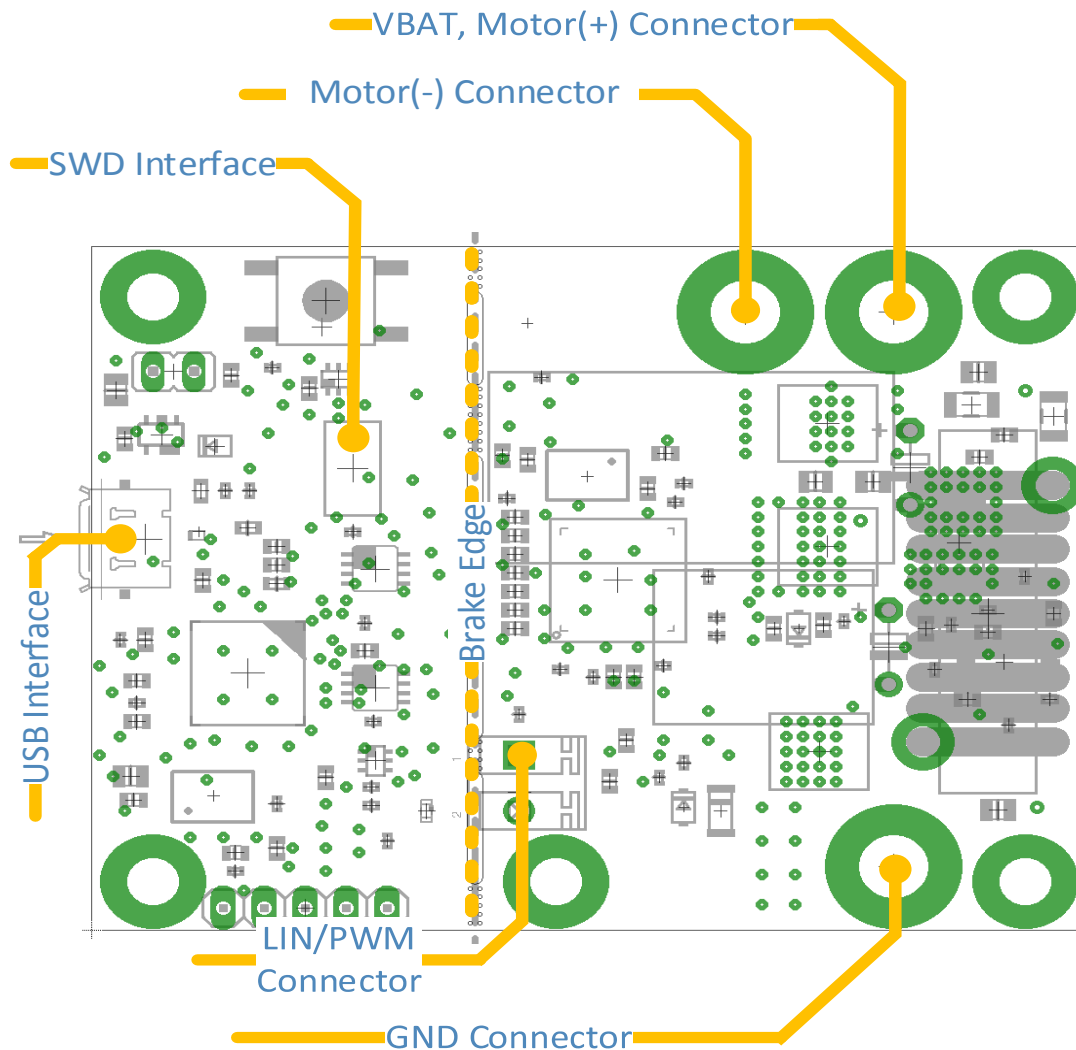


Figure 3 Interconnections Overview

2.5mm Screw Nut Connectors

Ground, voltagesupply (operating Voltage is documented in the datasheet) can be connected via 2.5mm Screw Nuts.

Motor contacts can also be accessed with 2.5mm screws. VBAT and MOTOR(+) have a shared connector. MOTOR(-) a GND have separate connectors.

LIN/PWM Connector

This connector is a direct access to the LIN/PWM Interface of the TLE9845QX. After Breaking the Debug-Interface. BSL-Mode can be used to perform programm updates via LIN Interface [Chapter 3](#).

USB

An Onboard-debugger is implemented on the TLE9845QX Appkit. The USB-Connection provides a Debug- and Serial-interface to the PC. More information in [Chapter 3.3](#).

SWD Interface

The SWD PIN-Header can be used optionally, instead of using the On-Board Debug Interface.

3 Communication Interfaces

3.1 LIN and uIO for LIN BSL

The device integrated LIN transceiver is connected to a dedicated Connector (see [Figure 3](#)). To integrate the device in a LIN network it is sufficient to use the single wire banana interface. The BSL interface is intended to program the device via LIN. For further information about the uIO interface see www.hitex.com/uio.

3.2 UART (Virtual COM PORT via USB)

A virtual COM port provided by Segger driver enables a PC – board – communication via UART. The UART2 module of TLE9845QX uses the pins P1.0 (transmit) and P1.1 (receive). Those are connected to the XMC4200, which emulates Rx and Tx on PC side with Segger firmware. Though they can be disconnected physically, bidirectional level shifters ensure that the XMC pins are hi-Z in case the virtual COM port is not used. By connecting the evaluation board to the PC a virtual COM port gets emulated by the Segger driver automatically. The virtual COM port will show up in the Microsoft® Windows® device manager.

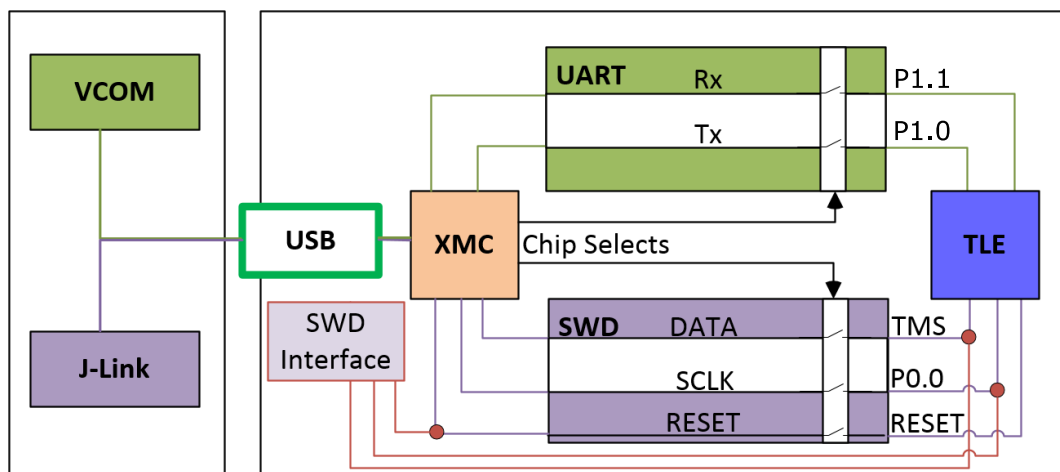


Figure 4 UART and Debugging

Note: Only one of the interfaces USB or SWD can be used at one time. While using the SWD interface the XMC is hold in reset. As long as a debugger is connected with the SWD interface it eliminates therefore debugging or UART via USB.

3.3 SWD-Debuginterface (J-Link via USB)

For serial wire debug the TLE984x uses the pins TMS (data) and P0.0 (clock). Level shifters between XMC4200 and TLE9845QX allow using P0.0, while it is not used for debugging.

The Segger J-Link module on board allows serial wire debugging via USB. Alternative debugging via SWD interface is possible to debug with another ISP than the onboard Segger e.g. U-Link2. Therefore the signals are routed through the 10 pin header SWD interface between the XMC4200 and the TLE984x. The pin configuration makes sure that the XMC is hold in reset while another debugger is physically connected to X11. The virtual COM port will be disabled, while the external ISP is connected.

4 Software Toolchain

4.1 Keil µVision 5

The recommended Integrated Software Development Environment is Keil® µVision5®. Infineons embedded Power family is supported. For more information about the Toolchain go to: www.keil.com

4.2 Infineon Config Wizard

In addition to the IDE, Infineon® provides the ConfigWizard. The tool is designed for code configuration, in combination with the IDE. Infineons Config Wizard can be downloaded via:

www.infineon.com/embeddedpower

4.3 TLE9845QX Installation

All embedded Power products can be installed to Keil® µVision5® via “Pack Installer”. Browsing to the Infineon chapter in “All Devices” will lead to the “TLE98xx Series”. The “.pack” file comes with several code examples, to provide an easy start up and speed up software development.

4.4 Debug Connection Setup

For a proper Flash and Debug Connection, Install V5.10 (or newer) from: www.segger.com/jlink-software.html
Keil® µVision5® has to be configured in the IDE Menu “Options for Target”. After connecting the USB-cable and power up the Evalboard, go to the “Debug” register-card and choose “J-LINK / J-TRACE Cortex” and press “Settings”.

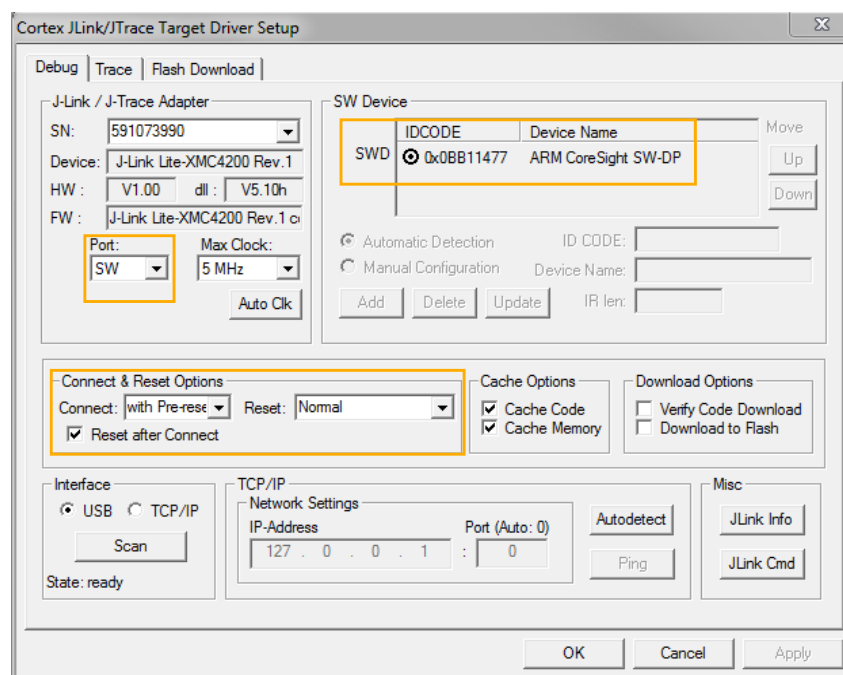


Figure 5 Debug and Flash Configuration

If the board has been connected successfully, the ARM IDCODE will be visible in the SW Device Window. If connection fails, “Connect & Reset Options” and “Port” window has to be checked.

Software Toolchain

4.5 GUI Description

4.5.1 General

The GUI (General User Interface) is a comfortable tool to control the functionality of the TLE9845 device over an USB interface.

The GUI-software was written in the programming language C# with MS Visual Studio 2015. The software will run under Windows 7, Windows 8 and Windows 10.

4.5.2 Open the GUI

The graphical user interface is shown in [Figure 6](#). It can be downloaded at www.infineon.com/TLE984x.

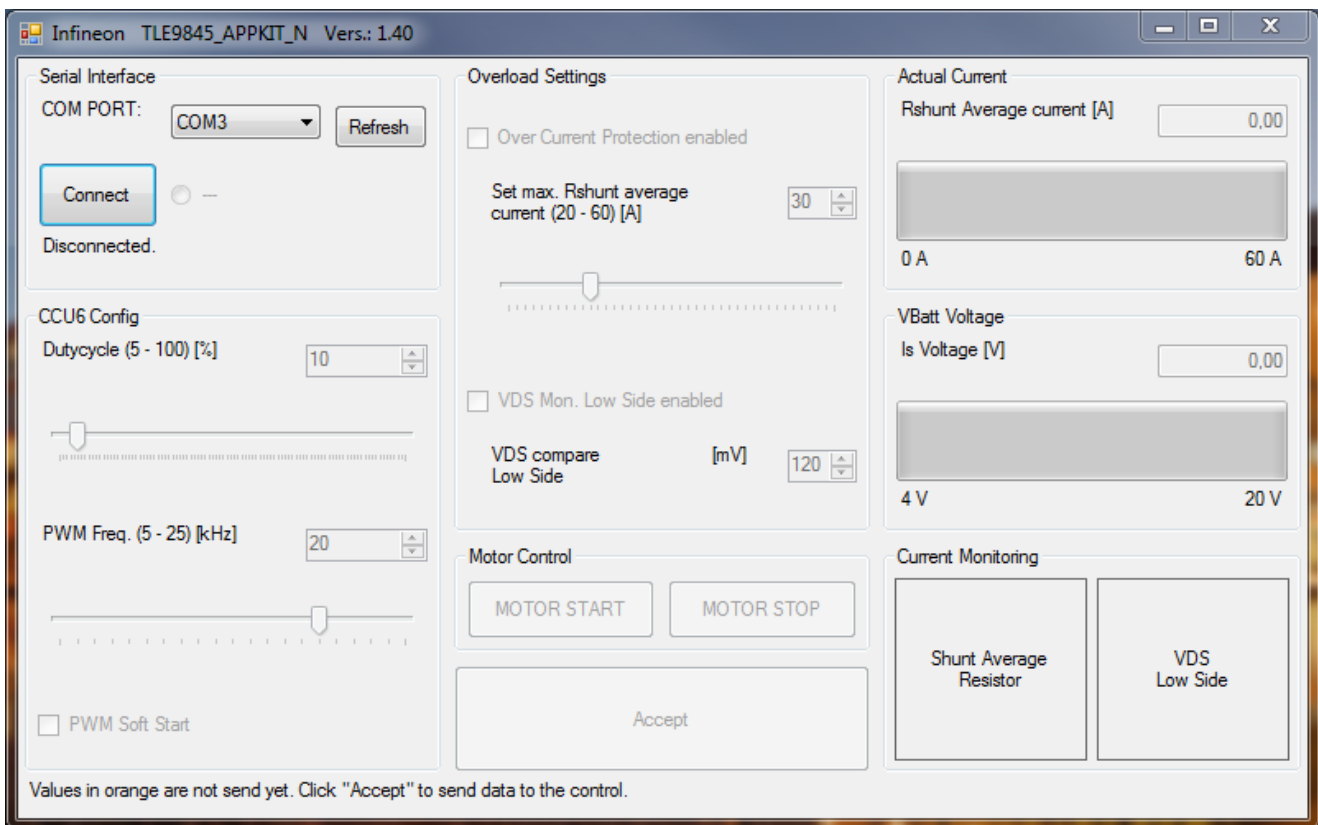


Figure 6 WindowsApplication_N_140 GUI: Unconnected

Software Toolchain

4.5.3 Connecting to the TLE9845 Device

Click on Refresh and select the COM PORT. Press Connect:

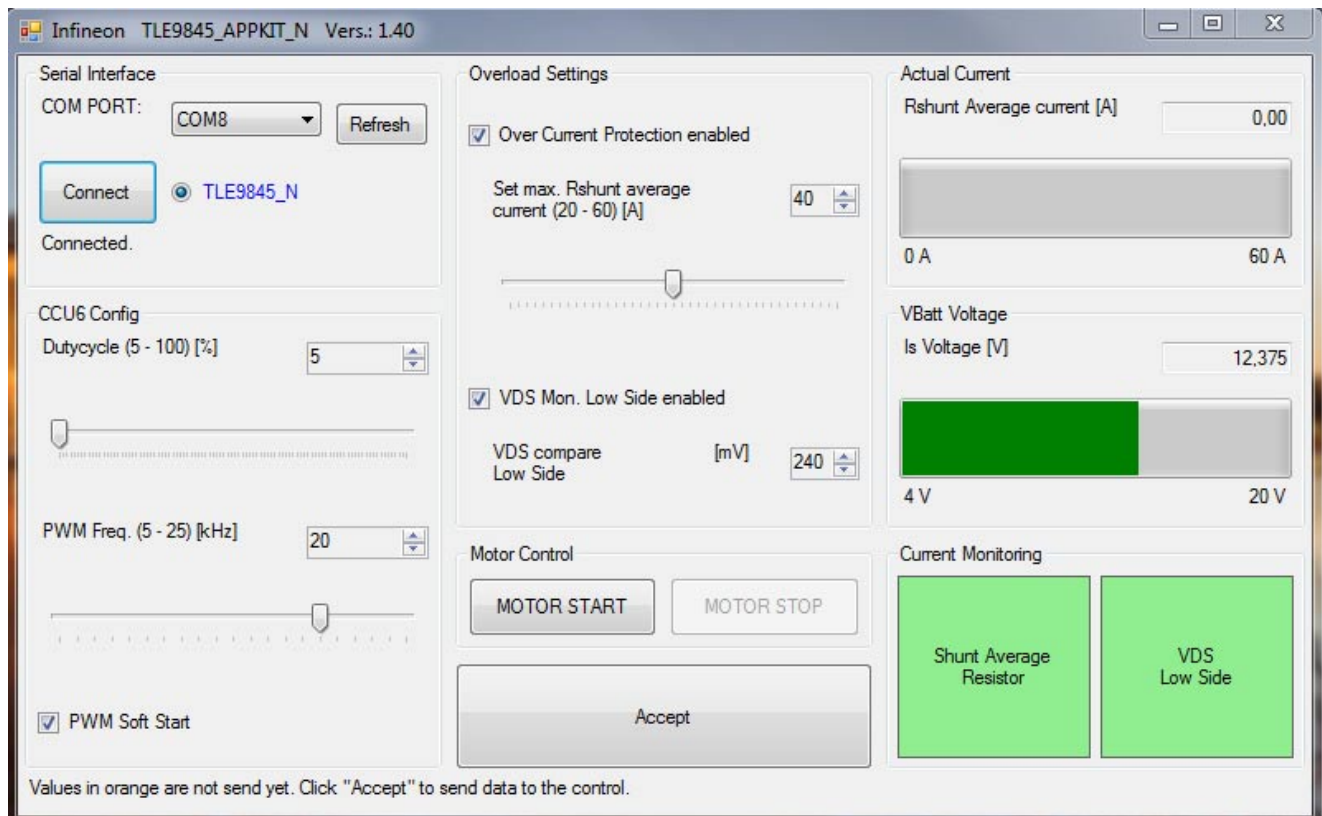


Figure 7 WindowsApplication_N_140 GUI: Connected

The PN_Appkit is now connected and can be controlled. The GUI gives analog information over the average current, measured at the Shunt resistor and the Supply Voltage.

5 Schematic and Layout

Schematic and Layout

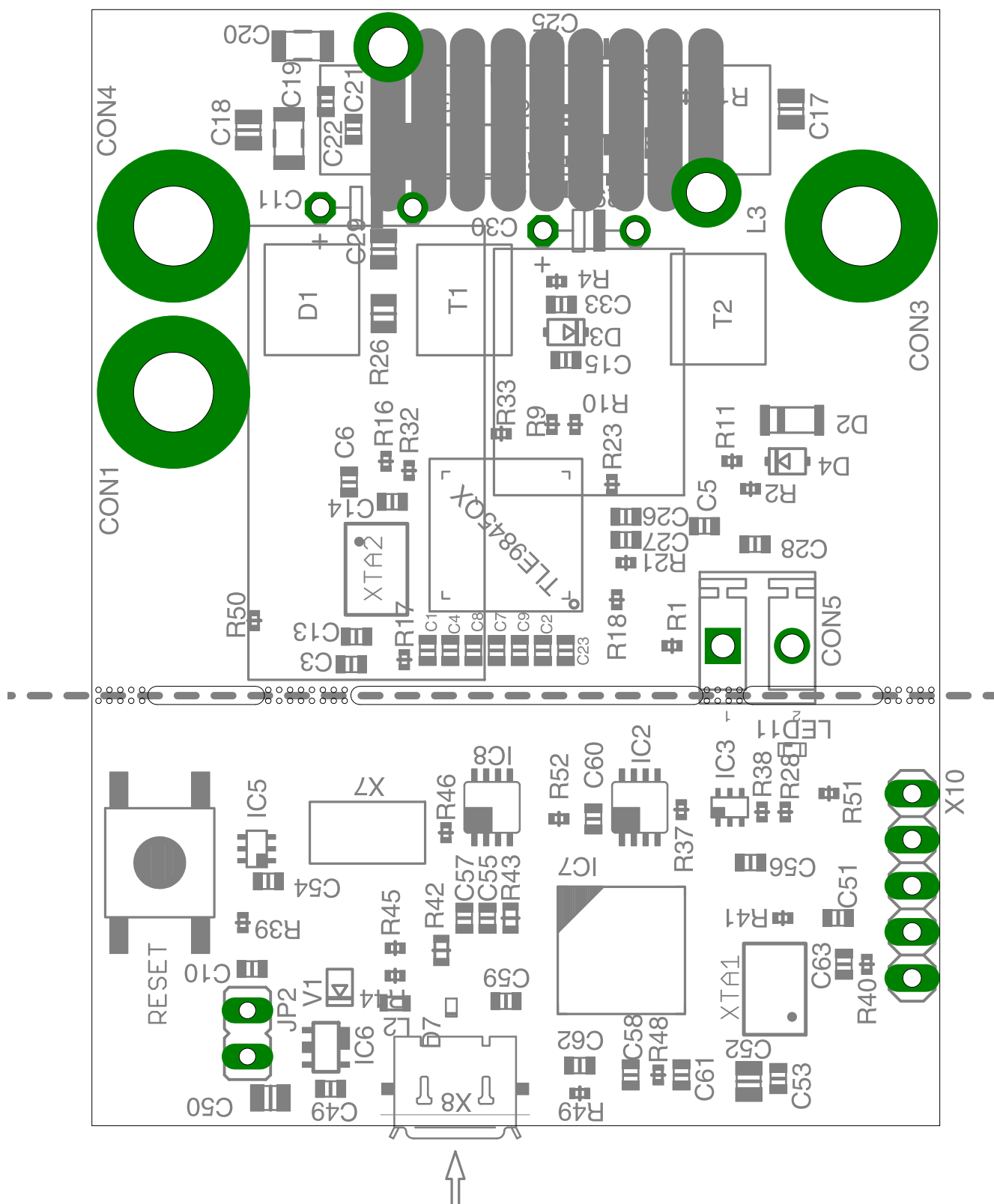
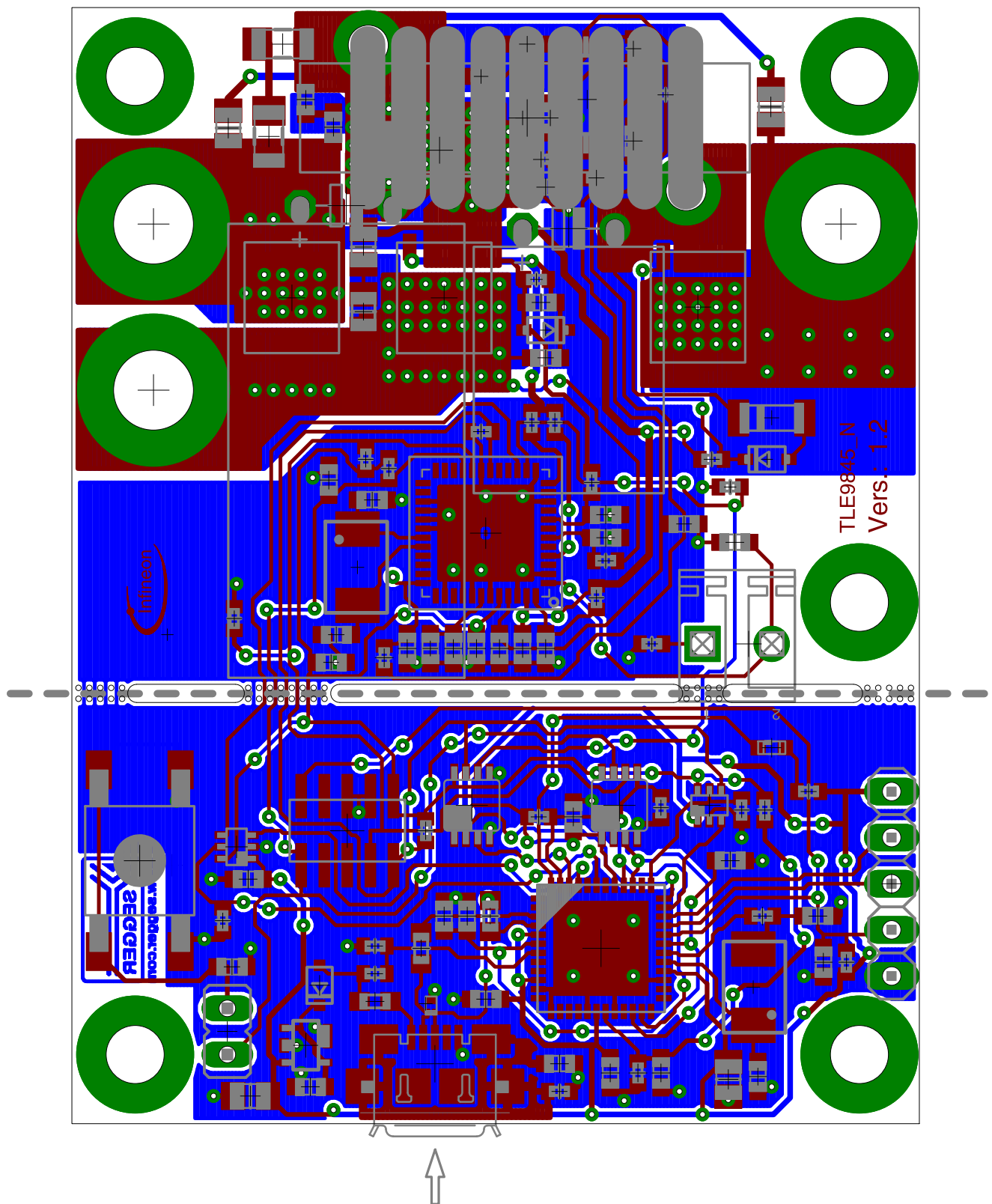


Figure 9 Parts placement

Note: This is a very simplified example of an application circuit and bill of material. The function must be verified in the application.

Schematic and Layout

**Figure 10** Layout

Note: This is a very simplified example of an application circuit and bill of material. The function must be verified in the application.

Revision History**6 Revision History**

Revision	Date	Changes
1.0	2017-04-07	Release State

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